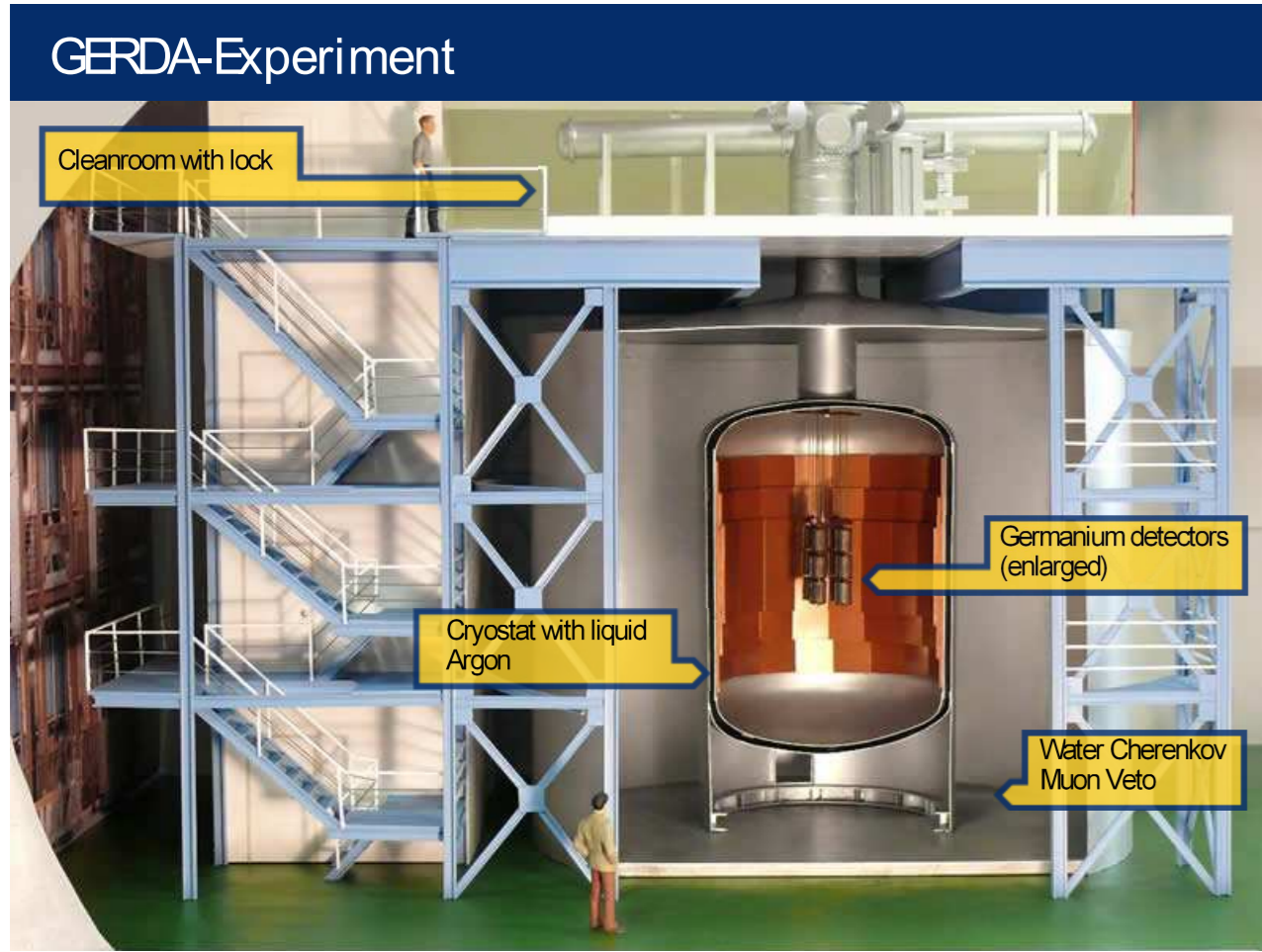


## Germanium Detector Array Experiment



Schematic of GERDA Experiment

- Search for **neutrinoless double beta decay** ( $0\nu\beta\beta$ ) of  $^{76}\text{Ge}$
- Operation of bare germanium diodes enriched in  $^{76}\text{Ge}$  in liquid argon (LAr)
- Located at Laboratori Nazionali del Gran Sasso (LNGS) under 3400 m.w.e. of rock
- **Best limit for  $^{76}\text{Ge}$**   
 $T_{1/2}^{0\nu} > 2.1 \cdot 10^{25} \text{ yr (90\% C.L.)}$   
reached in **June 2013 (Phase I)**
- Now updating experimental apparatus to Phase II

## Phase II of the GERDA Experiment

- Sensitivity on  $T_{1/2}^{0\nu}$  is proportional to

$$\epsilon a \sqrt{\frac{M \cdot t}{BI \cdot \Delta E}}$$

$\epsilon$ : detection efficiency,  $a$ : abundance of  $^{76}\text{Ge}$ ,  $M$ : target mass [kg],  $t$ : exposure [yr],  $BI$ : background index [cts/(keV·kg·yr)],  $\Delta E$ : energy resolution around ROI at  $Q_{\beta\beta} = 2039 \text{ keV}$

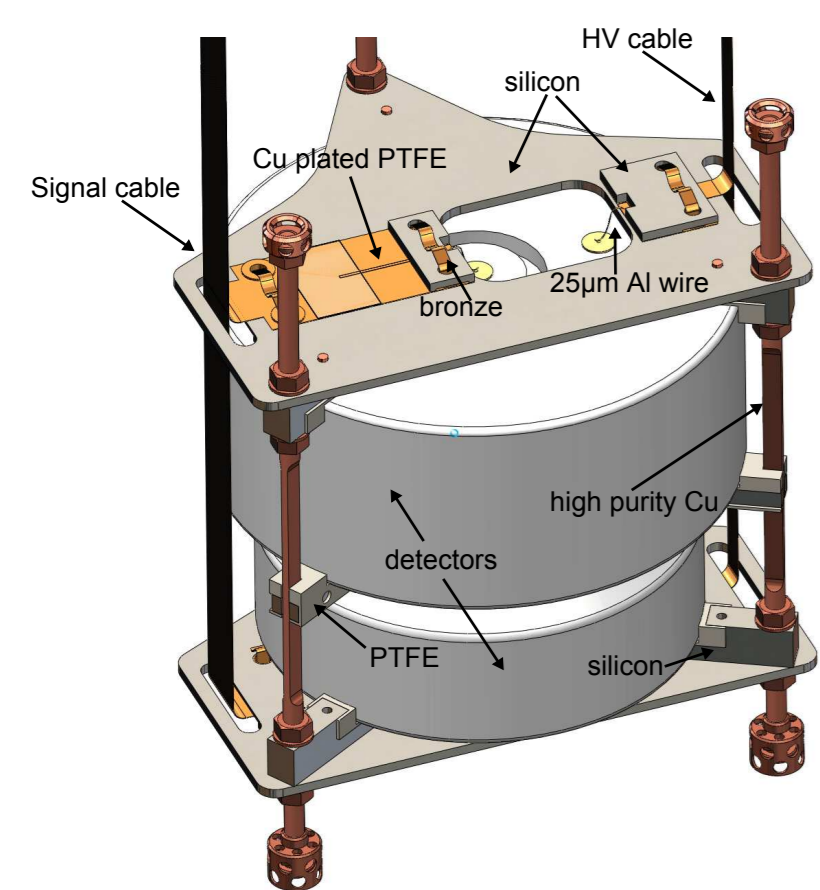
- Efficiency and abundance cannot be increased much more
- Increase of target mass by 20 kg with additional custom made detectors (BEGe)

- Reduction of background index by factor 10 to  $< 10^{-3} \text{ cts/(keV}\cdot\text{kg}\cdot\text{yr)}$  with
  - Active veto by reading out scintillation light of LAr
  - Improved pulse shape discrimination capabilities of new detectors
  - Use of even more radio-pure materials and reduction of mass close to the detectors, e.g. detector holders and front-end electronics
- Further improvement of energy resolution  $\Delta E$  by better front-end electronics and new detectors

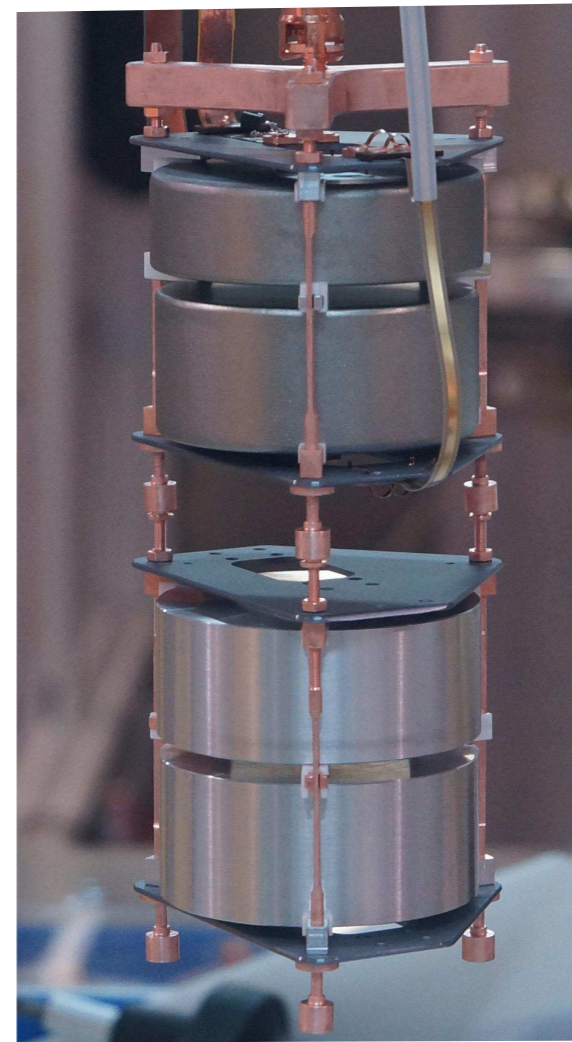
→ Aim for Phase II sensitivity is

$$T_{1/2}^{0\nu} > 10^{26} \text{ yr}$$

## Detector holder design



CAD of detector holder

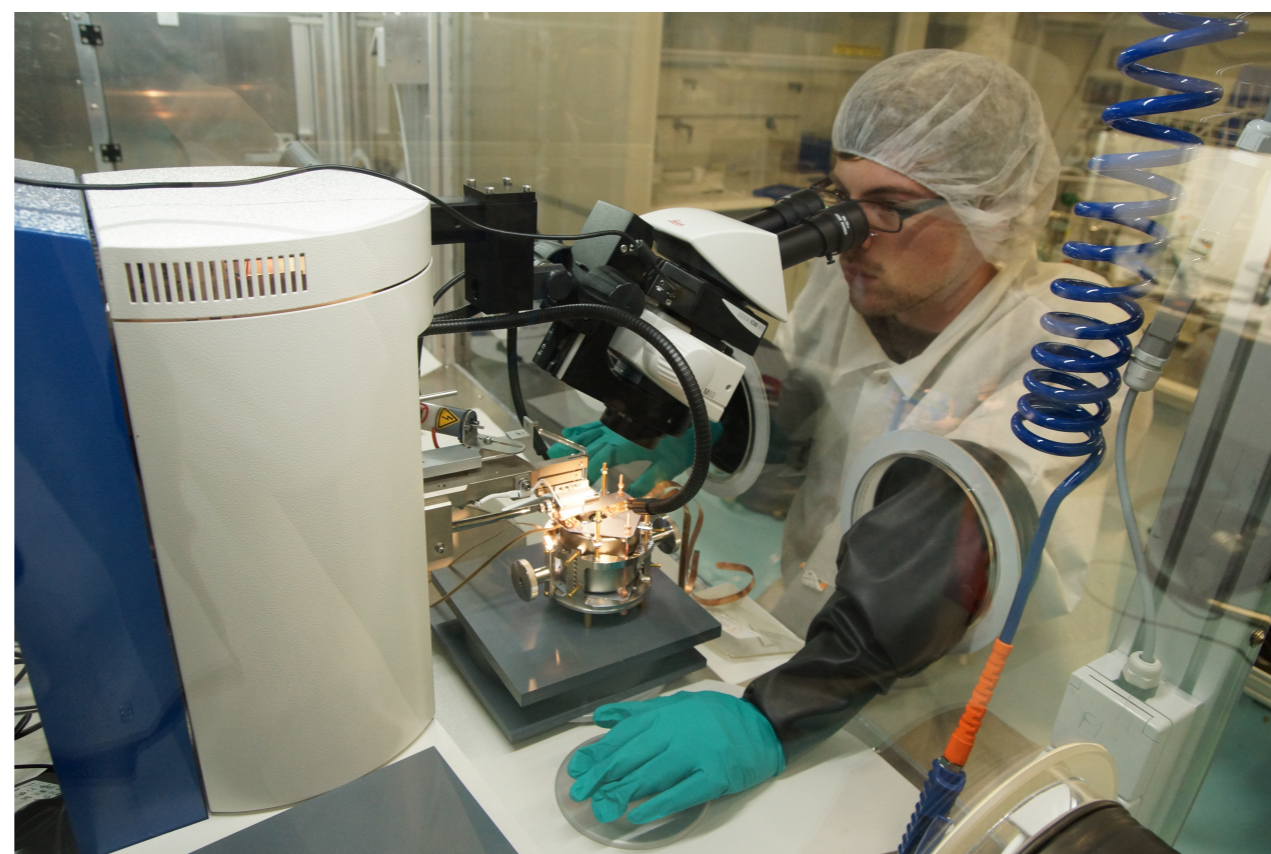


Assembly of two detector pairs

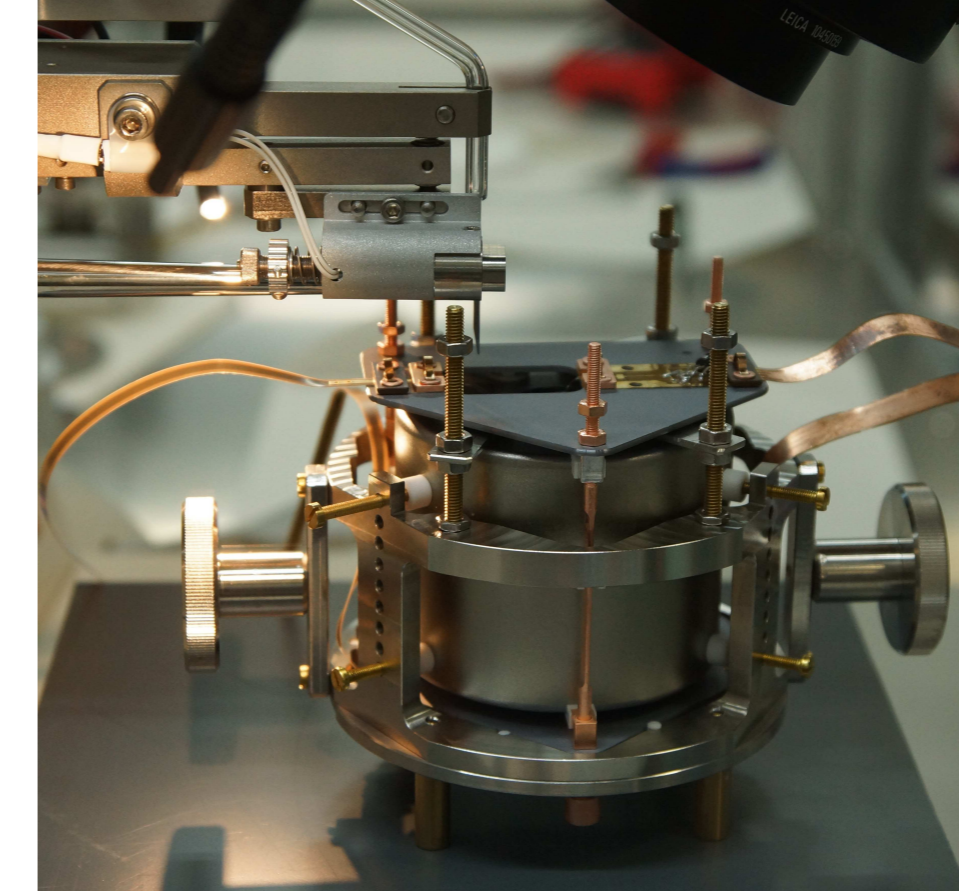
- Two new detectors are assembled as a pair
- First stage of front-end electronics & HV strip integrated into holder assembly
- Reduction of holder mass per kg detector mass is important since BEGe's are smaller than semi-coaxial detectors
- Most of the copper replaced by intrinsically pure monocrystalline silicon (known from neutron activation analysis)
- **New contacting scheme (wire bonding)** allows a holder with reduced mass and material strength, i.e. silicon

## Detector contacting

### Wire bonding



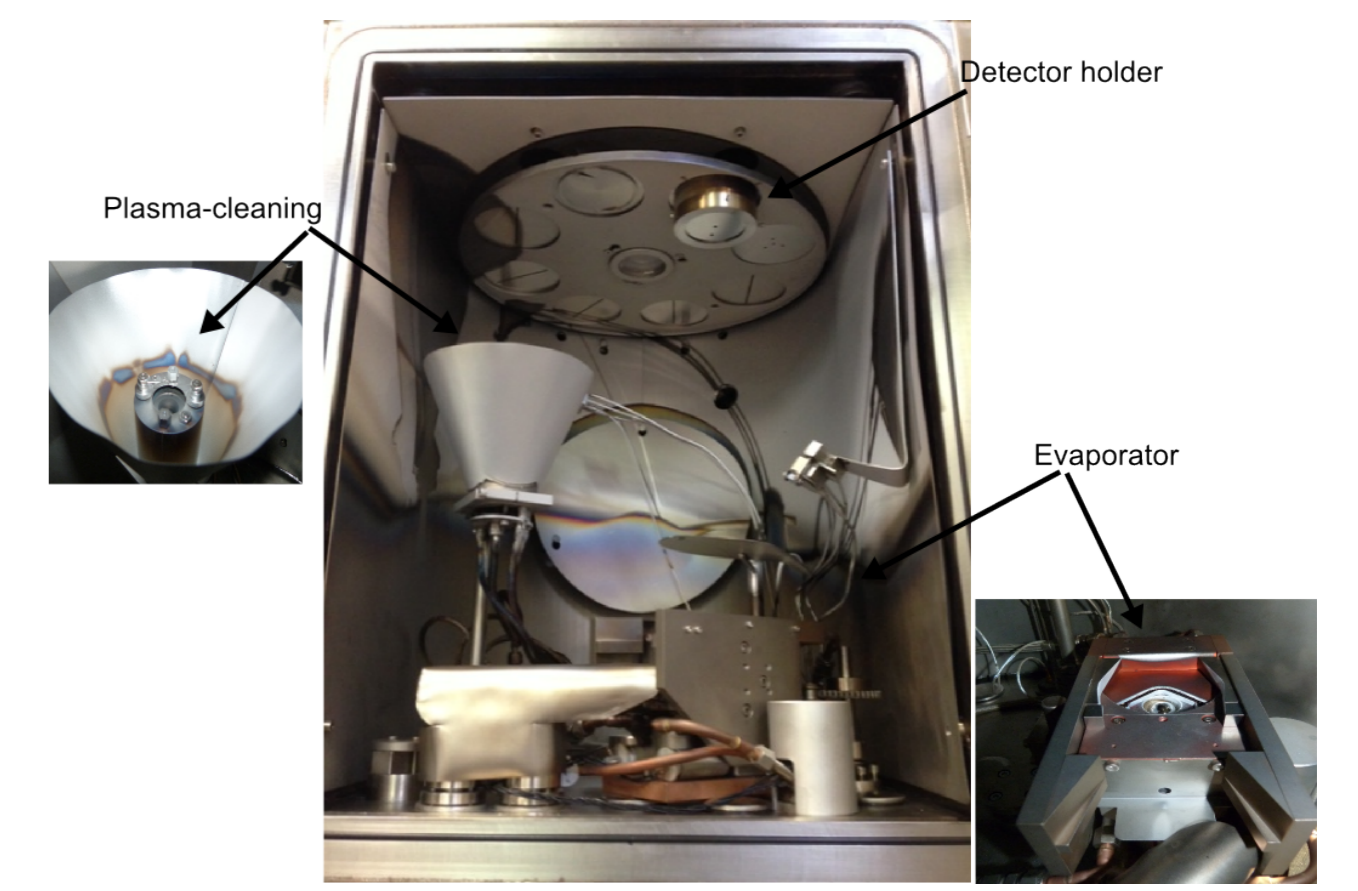
Bonding machine located in Germanium Detector Lab



Close-up of bonding arm & detectors in mounting jig

- Wire bonding well established in chip industry & for Si detectors, but not regularly used with large volume germanium diode detectors
- Small masses of bonding wire (25  $\mu\text{m}$  wire thickness) ensure low background contribution
- **Challenges:**
  - Bonds have to be stable during immersion in LAr & warming up ✓
  - Bonding must not damage sensitive read-out electrode ✓
  - Usage of bonding machine in glove box ✓

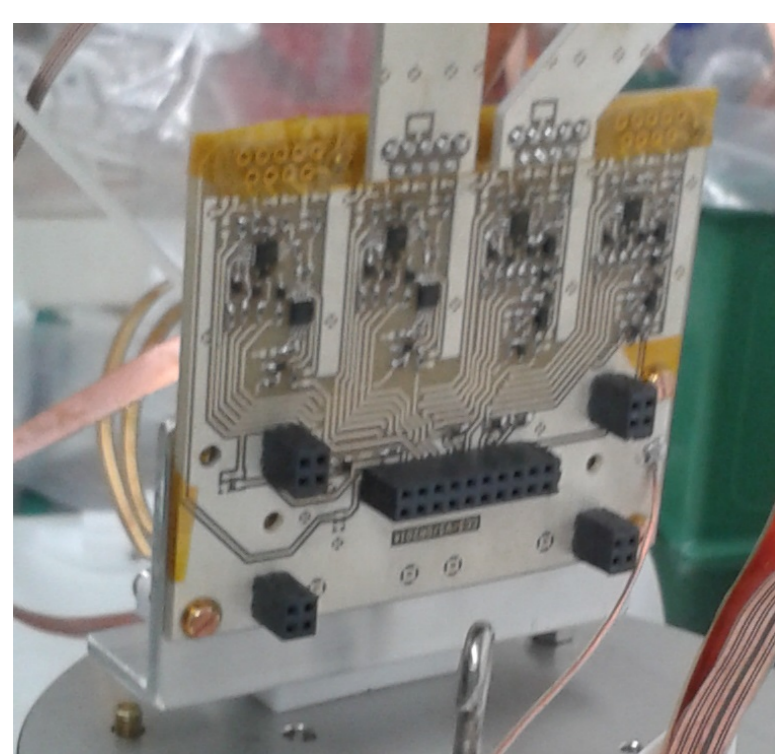
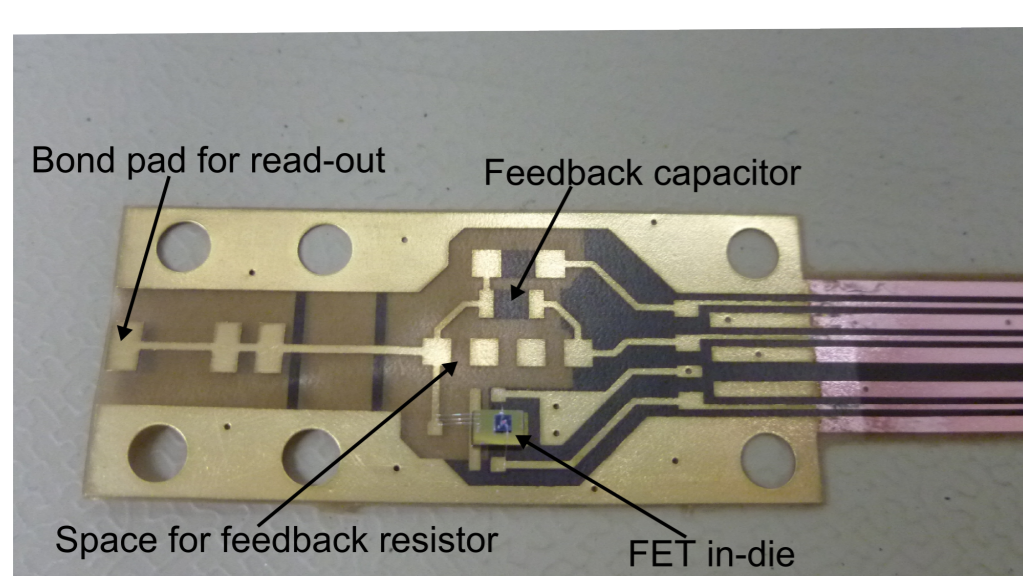
### Metalization of detectors



Thin film deposition machine

- Metalization of read-out & HV electrodes needed for **ohmic contact at cryogenic temperatures & reliable wire bonding**
- Aluminum e-gun evaporation chosen as high quality deposition process
- Screened high purity material (6N) and film thickness (600 nm) ensure small background
- **Process developed at TUM** and integrated into production process in close collaboration with detector vendor Canberra SNV, Olen

## Front-end electronics

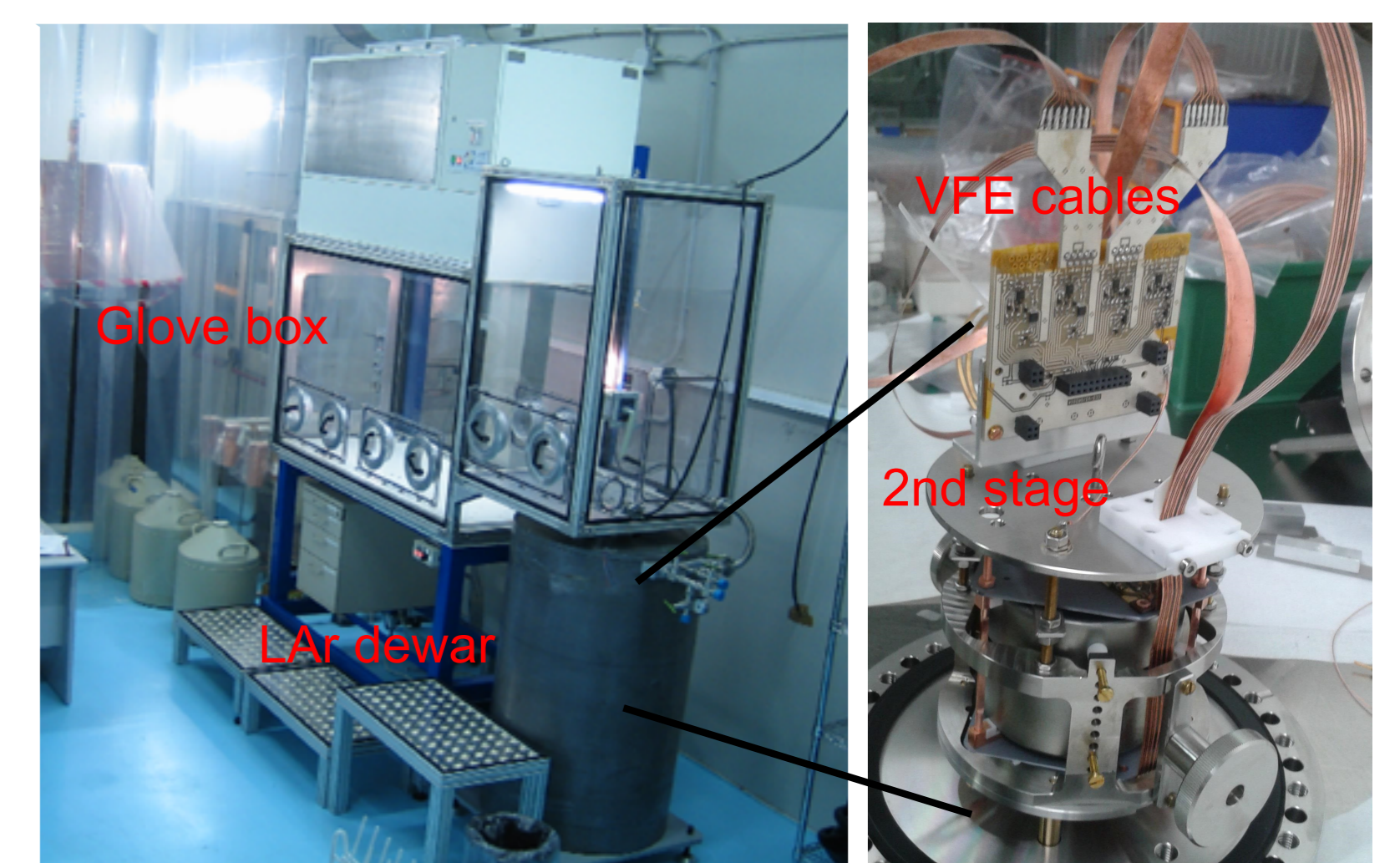


1st & 2nd stage of front-end electronics

- Concept of GERDA Phase II front-end electronics is **separation of 1st & 2nd stage of charge sensitive pre-amplifier**
- Close-by 1st stage (6mm) reduces noise due to additional capacitances & pick up
- Electronically more complex 2nd stage put far away from detectors (~50cm) to reduce background contribution
- **Description of 1st stage**
  - Components integrated on signal cable
  - FET in-die with low capacitance
  - Stray capacitance of traces as feedback capacitor
  - Radiopure resistor with high resistance ( $\sim 10^9 \Omega$ ) still to be chosen

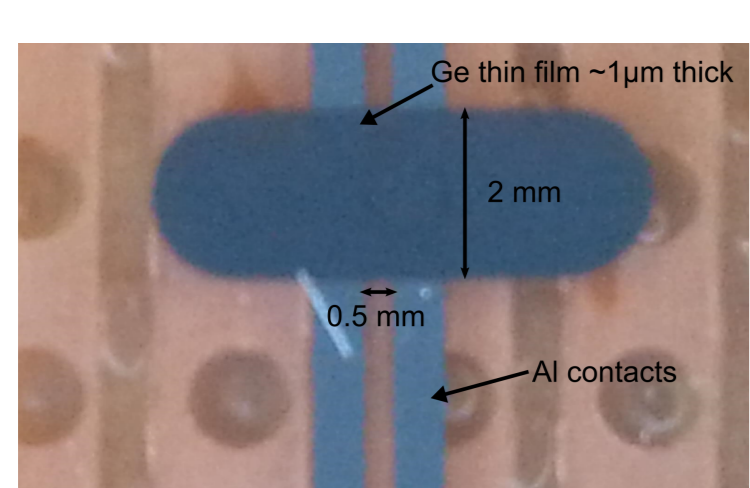
## Integration test & first results

- Test of complete assembly in liquid argon cryostat
- Detector assembly built up in glove box
- Use of prototype detectors (from non-enriched material)
- Investigation of **noise** ✓, **microphonics** ✓, **handling**, **stability**, **energy resolution** ✓, **pulse shape discrimination performance** ongoing
- Test of new front-end electronics in close to final setup with realistic VFE cable length
- Measurements with  $^{228}\text{Th}$  source for energy resolution and pulse shape performance testing

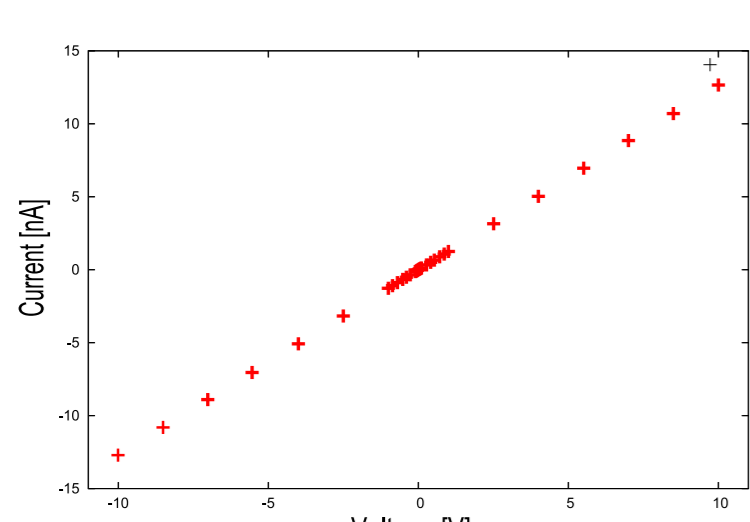


Testing apparatus in underground Germanium Detector Lab (GDL)

## Feedback resistor development at TUM



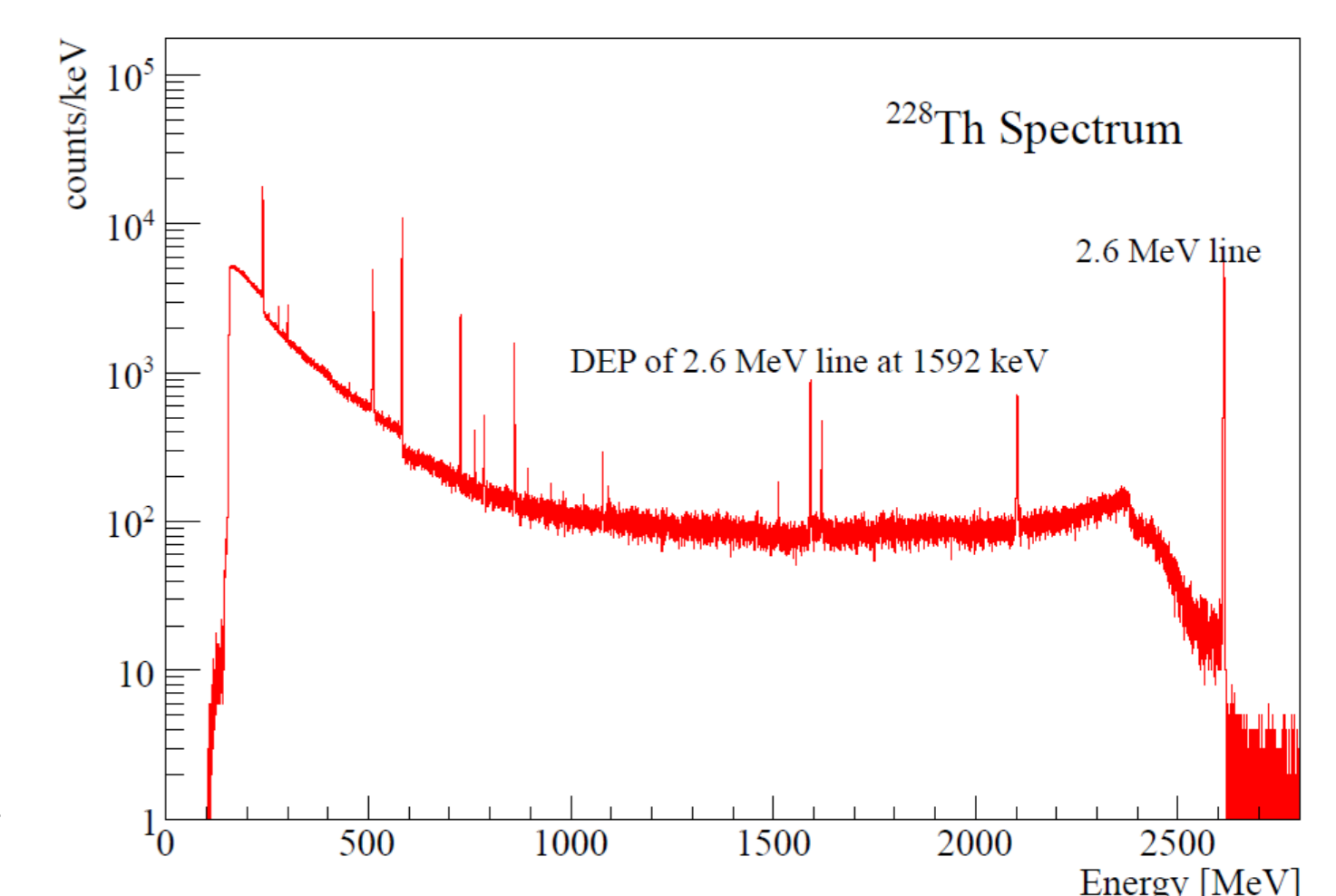
Amorphous germanium resistor sample



Linearity curve of sample resistor

- Amorphous germanium (a-Ge) is radio-pure & highly resistive at LAr temperature
- MAJORANA Experiment uses a-Ge resistors
- High resistance reduces thermal noise component
- Thin film deposition techniques used for production
- High purity quartz as substrate
- **Status:**
  - Achieved correct resistance values with high reproducibility ✓
  - Verified linearity of a-Ge over wide voltage range ✓
  - Resistance increases over time when stored in room atmosphere
  - Impact of possible cryogenic or inert atmosphere storage being investigated

- Energy resolution of BEGes in **Phase I with not close VFE (CC2): 3 keV @ 2.6 MeV** during calibrations
- With **new VFE and 2nd stage (CC3)** during integration tests in LAr and **final cable length: 2.7 keV @ 2.6 MeV**
- Resolution in **vacuum cryostat** (under ideal conditions): **2.4 keV @ 2.6 MeV**
- Pulse shape capabilities at least as good as in Phase I - still being investigated
- **Excellent energy resolution in ultra low background setup is main advantage of germanium detectors**



Peak [keV]	Fitted peak pos. [keV]	FWHM [keV]	Rel. resolution [%]
583.191	583.09 ± 0.00	1.49 ± 0.00	0.26
1592.537	1592.17 ± 0.01	2.14 ± 0.02	0.13
1620.500	1620.03 ± 0.01	2.12 ± 0.03	0.13
<b>2614.533</b>	<b>2614.20 ± 0.00</b>	<b>2.71 ± 0.01</b>	<b>0.10</b>